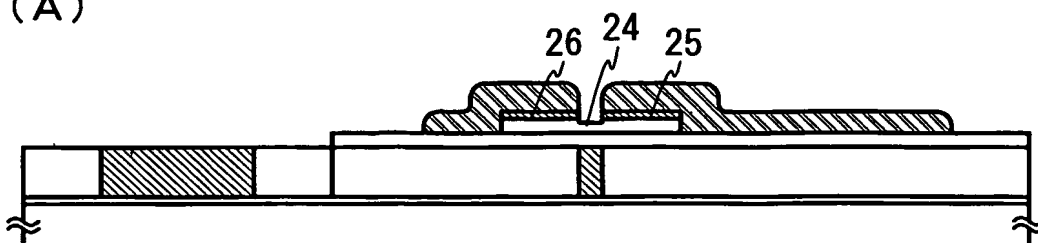


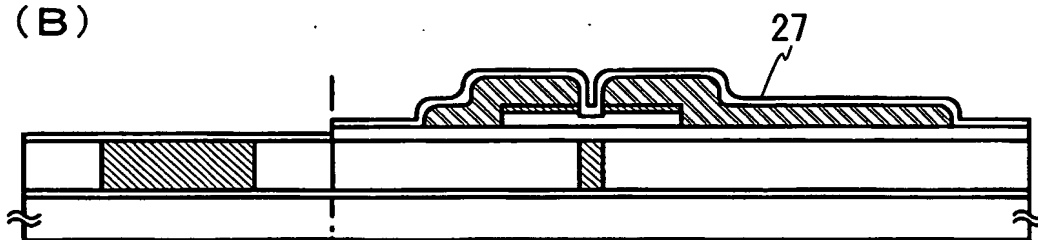
FIG.1

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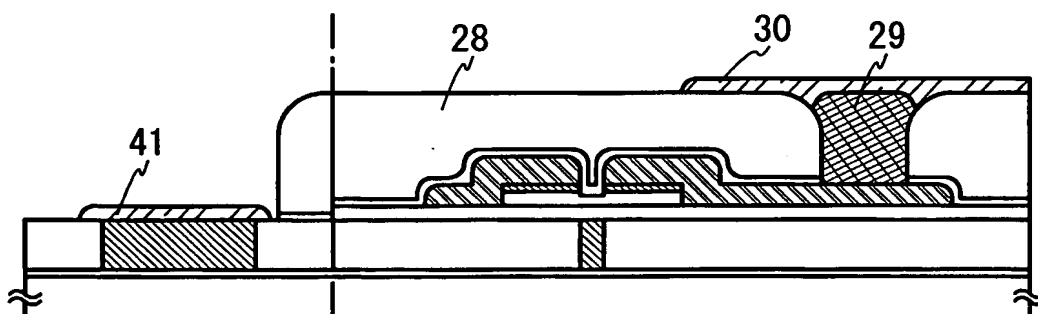
(A)



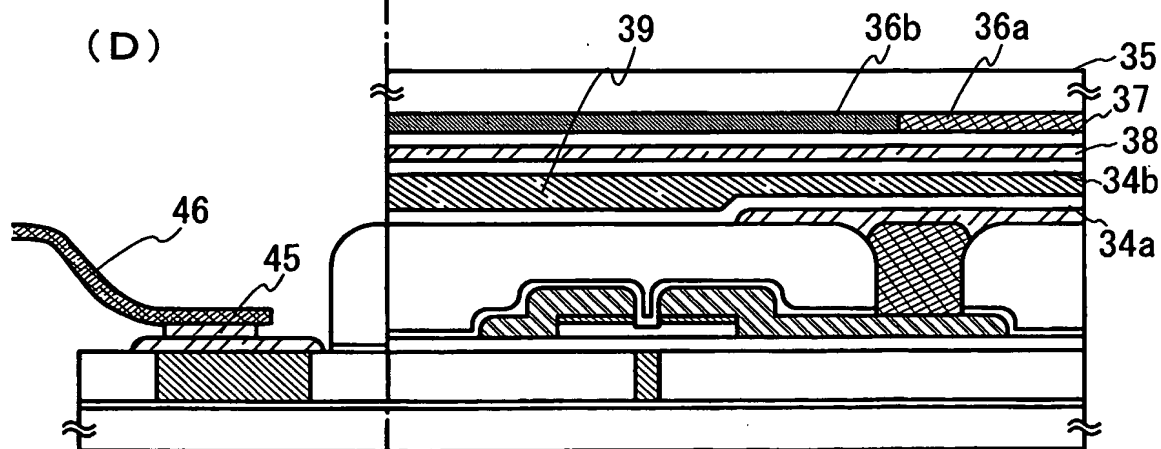
(B)



(C)



(D)



terminal portion

pixel portion

**FIG.2**

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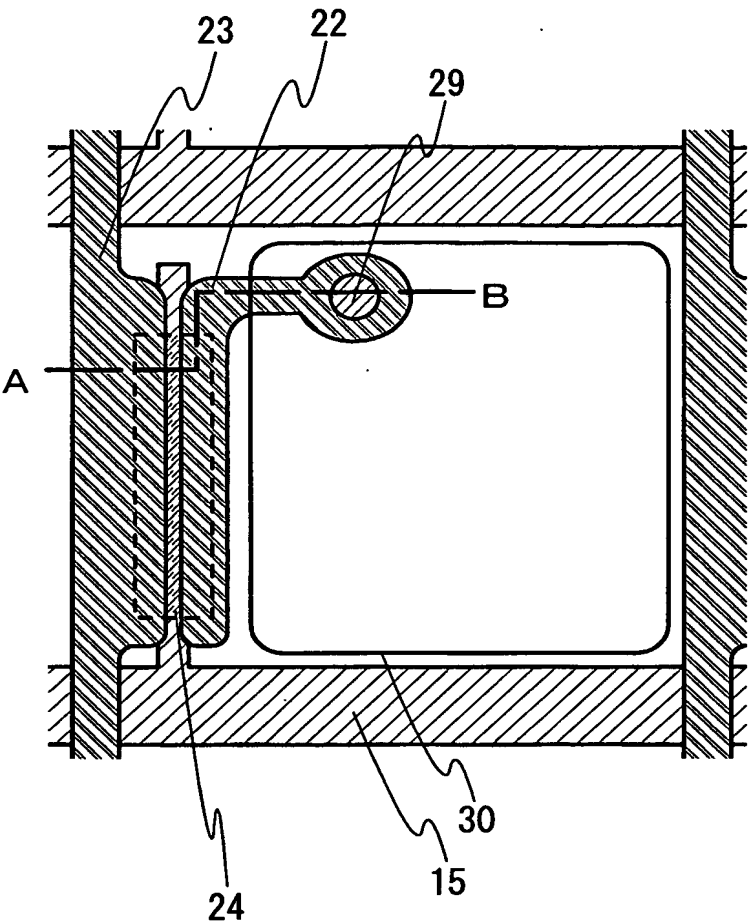
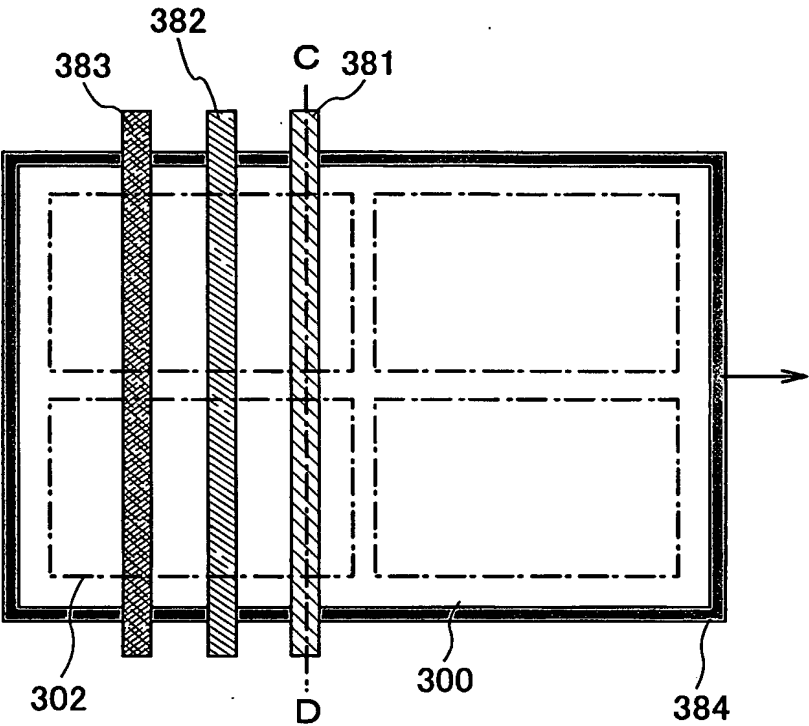


FIG.3

(A)



(B)

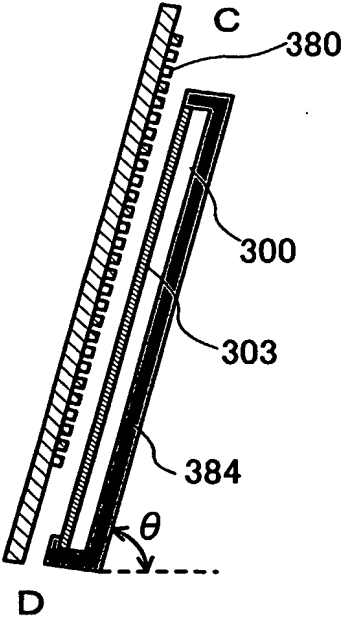


FIG.4

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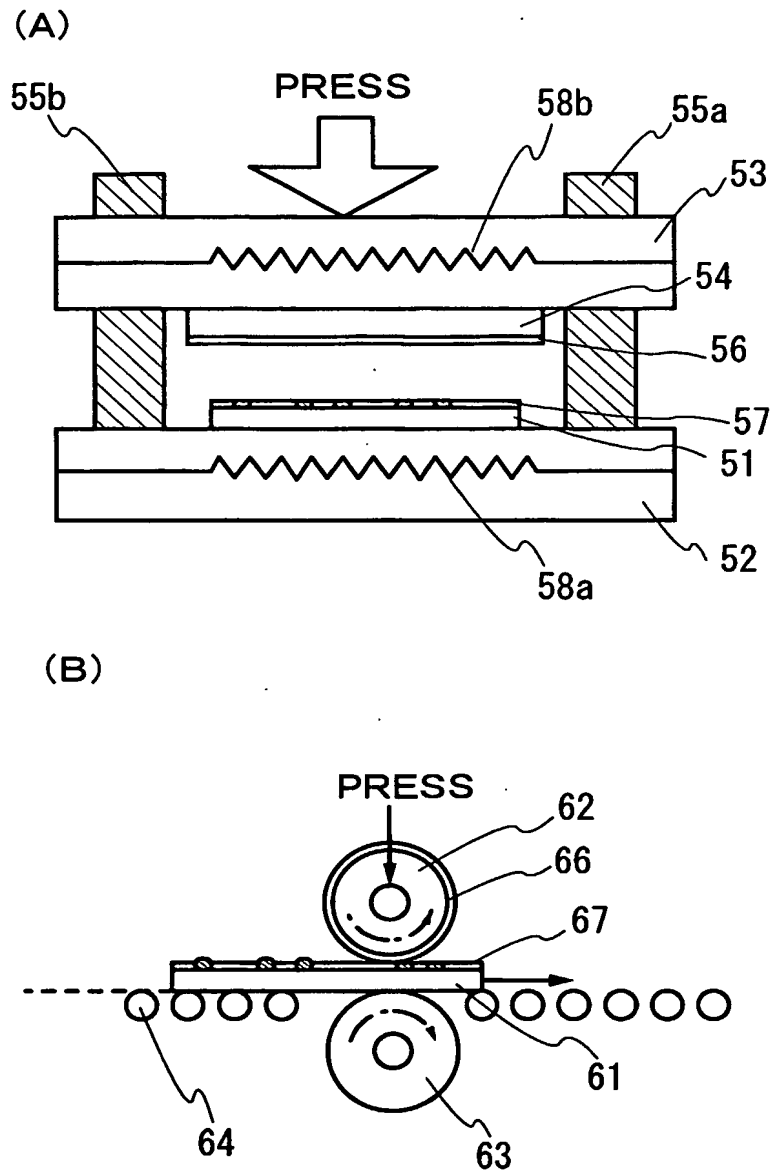


FIG.5

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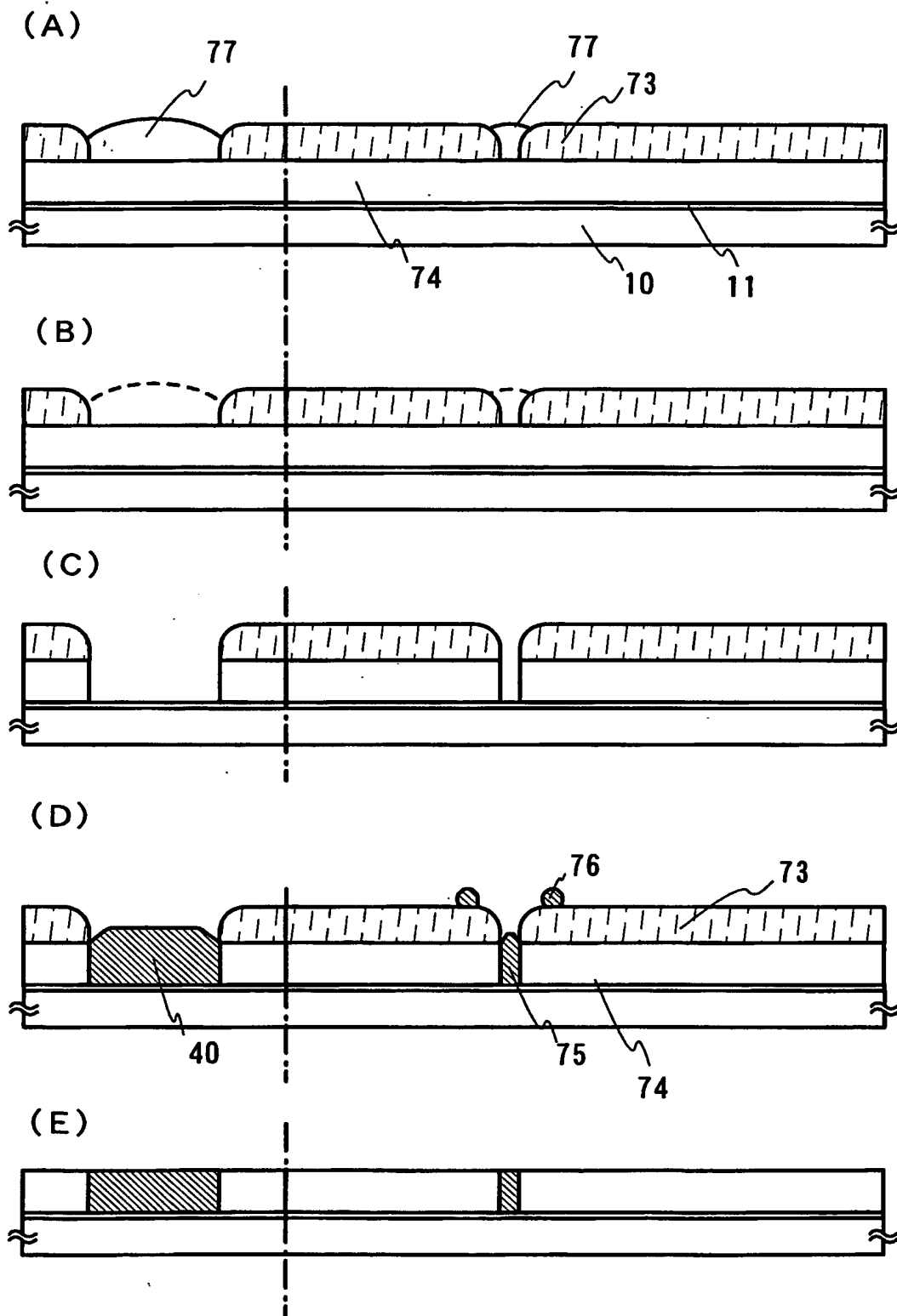


FIG.6

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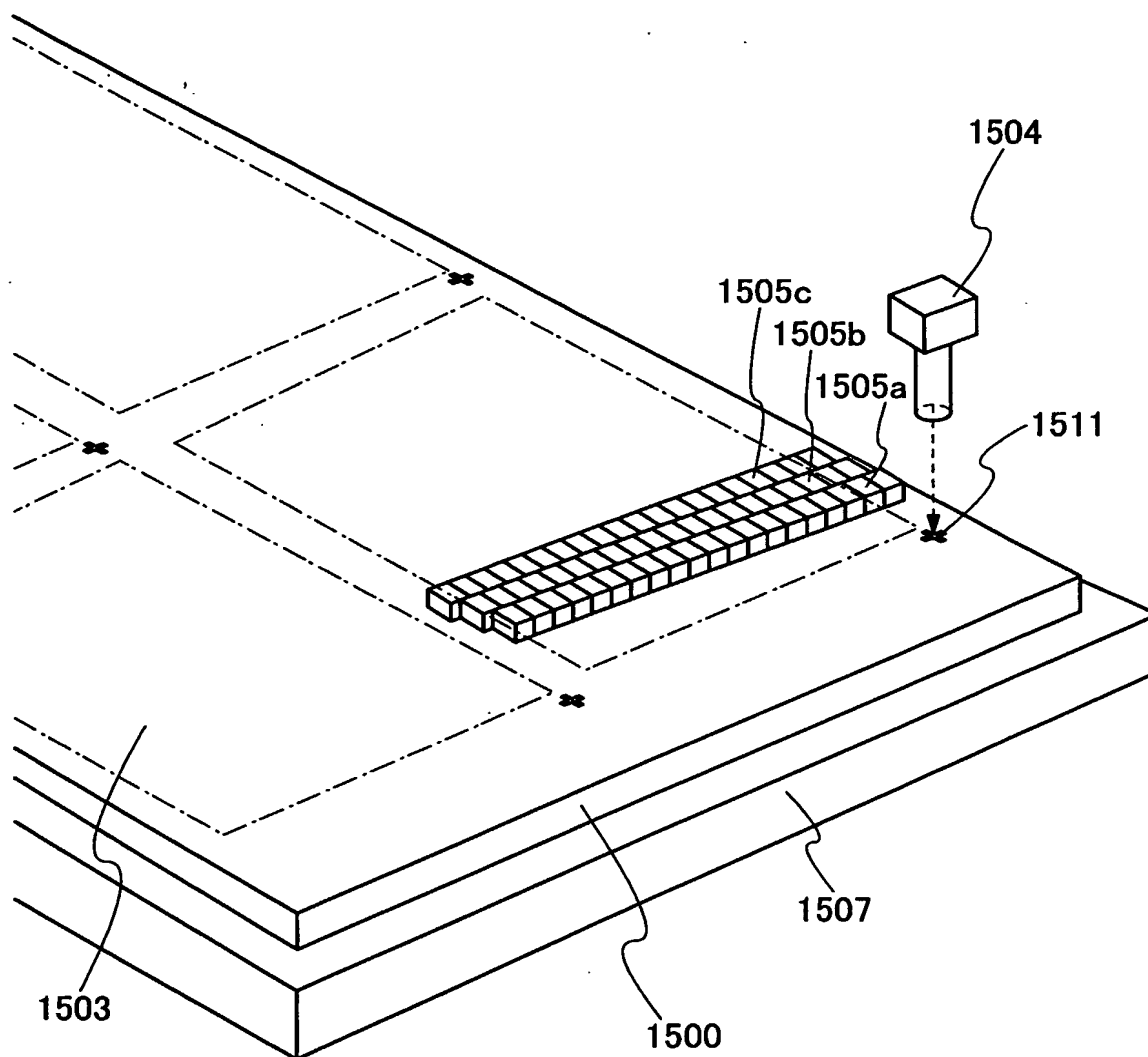


FIG. 7

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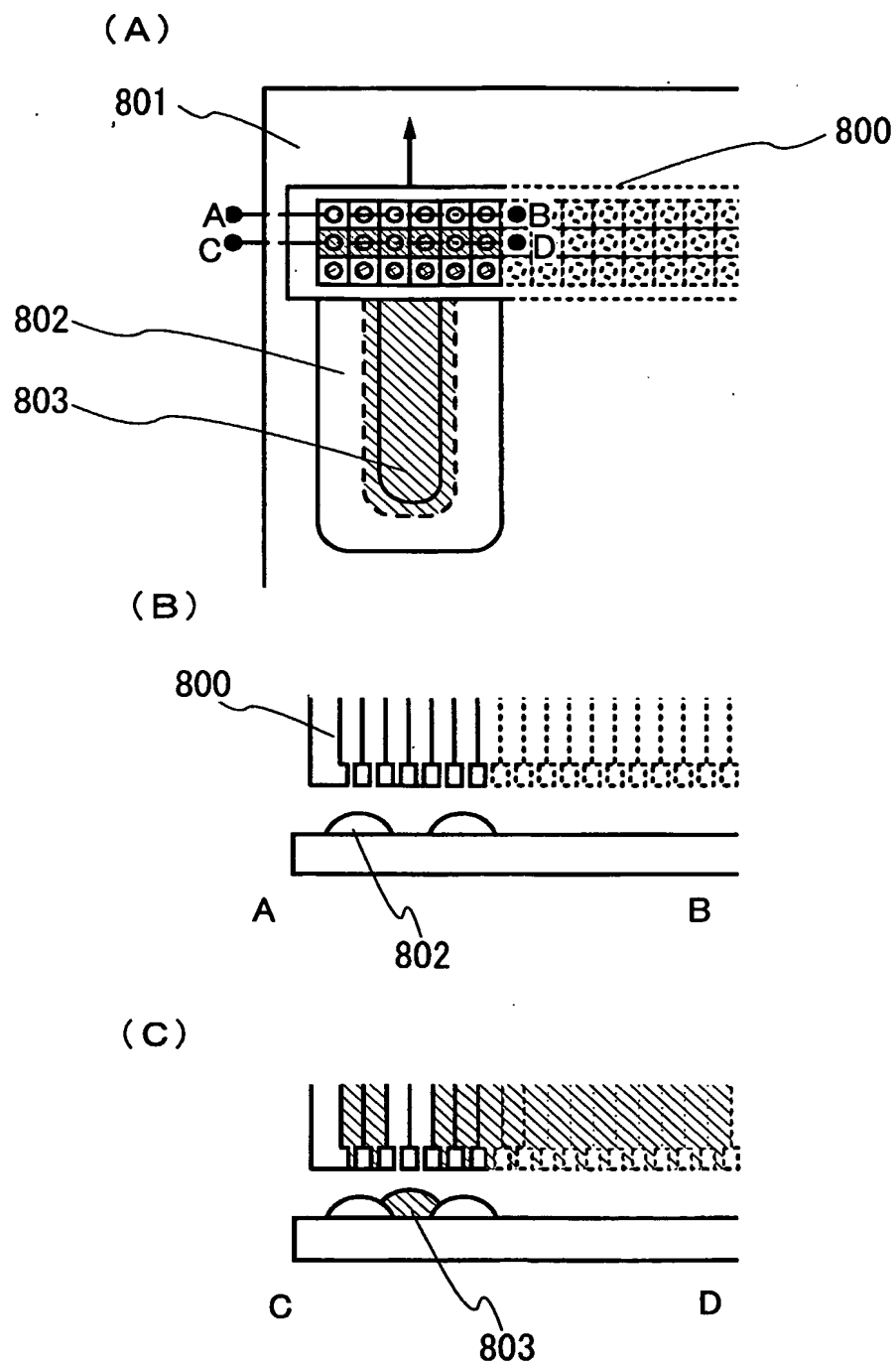


FIG.8



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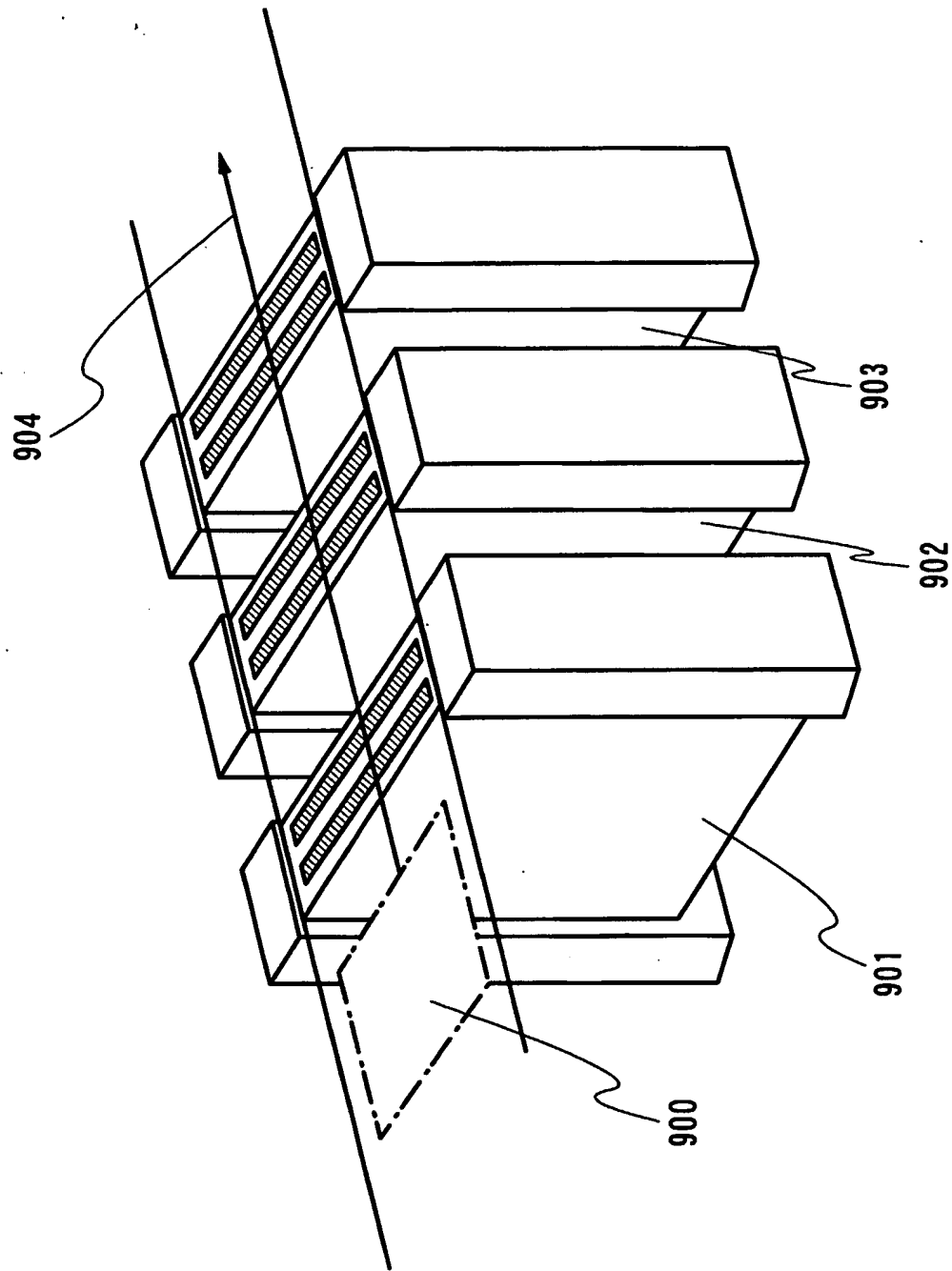


FIG. 9

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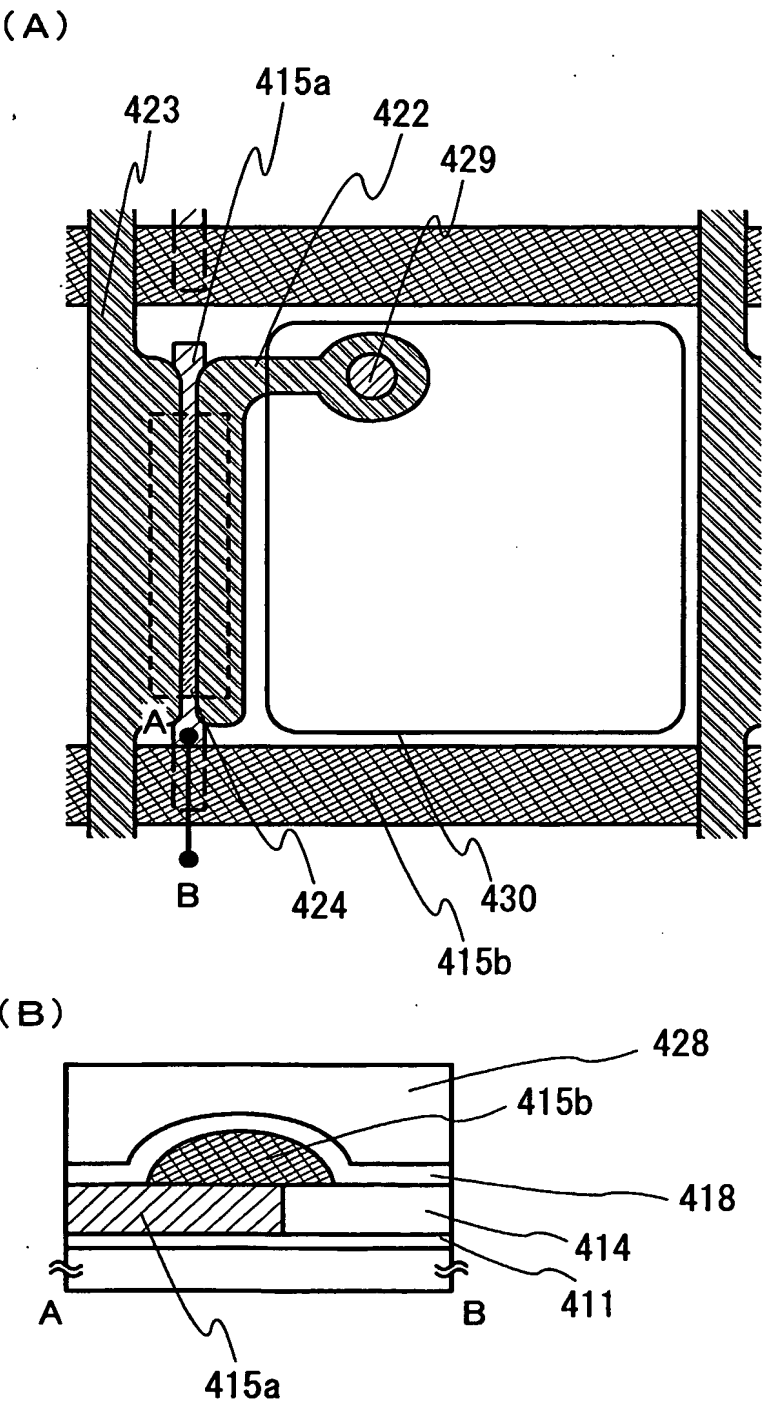


FIG.10

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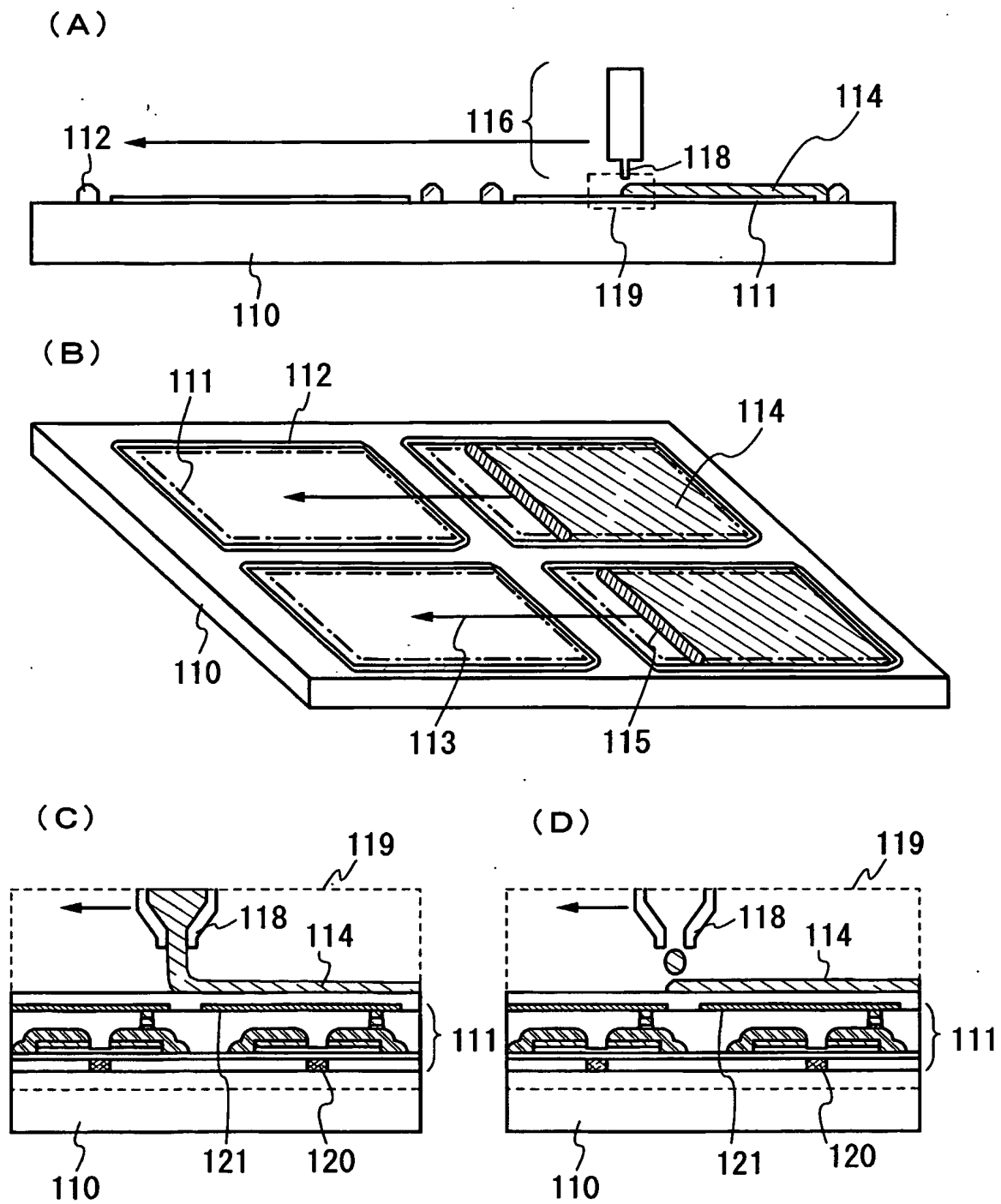


FIG.11

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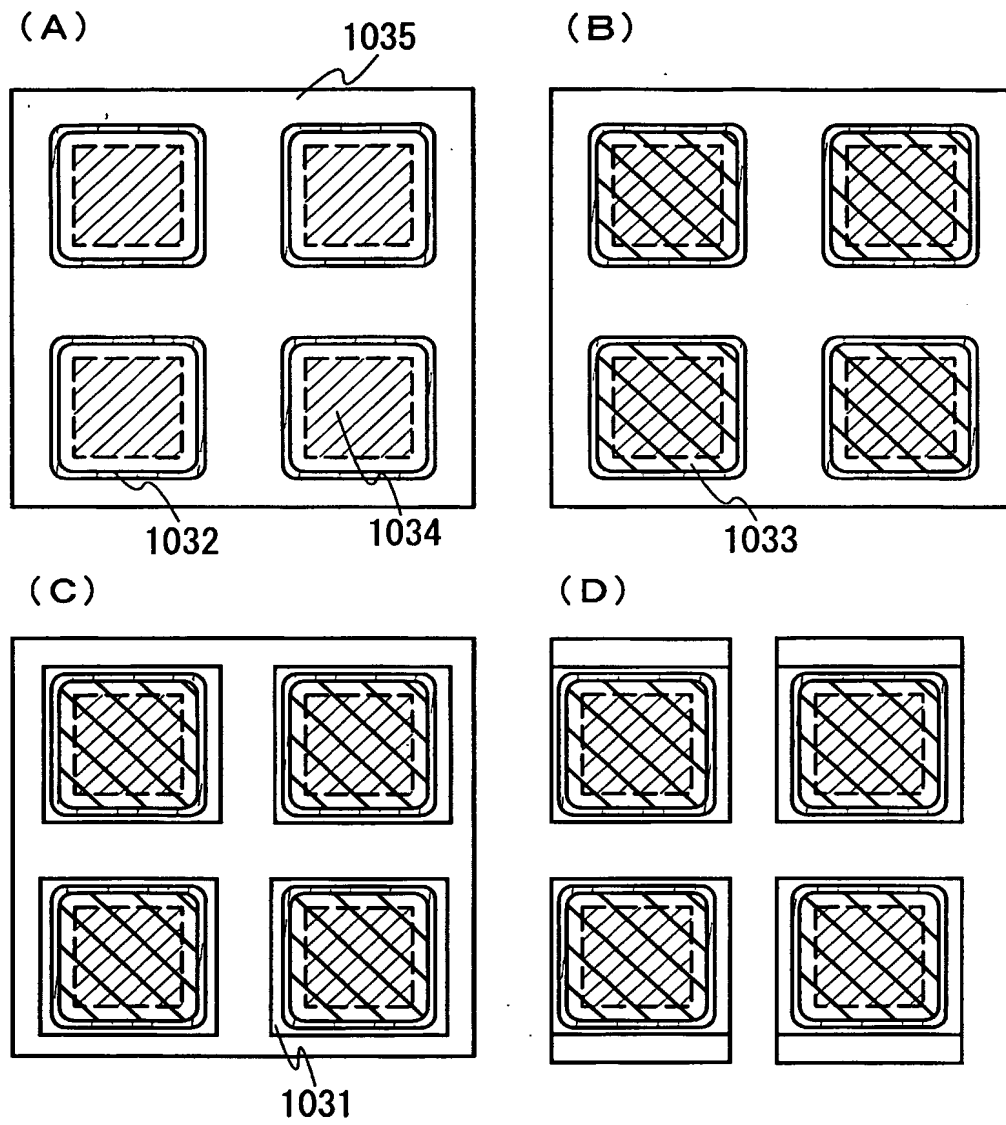
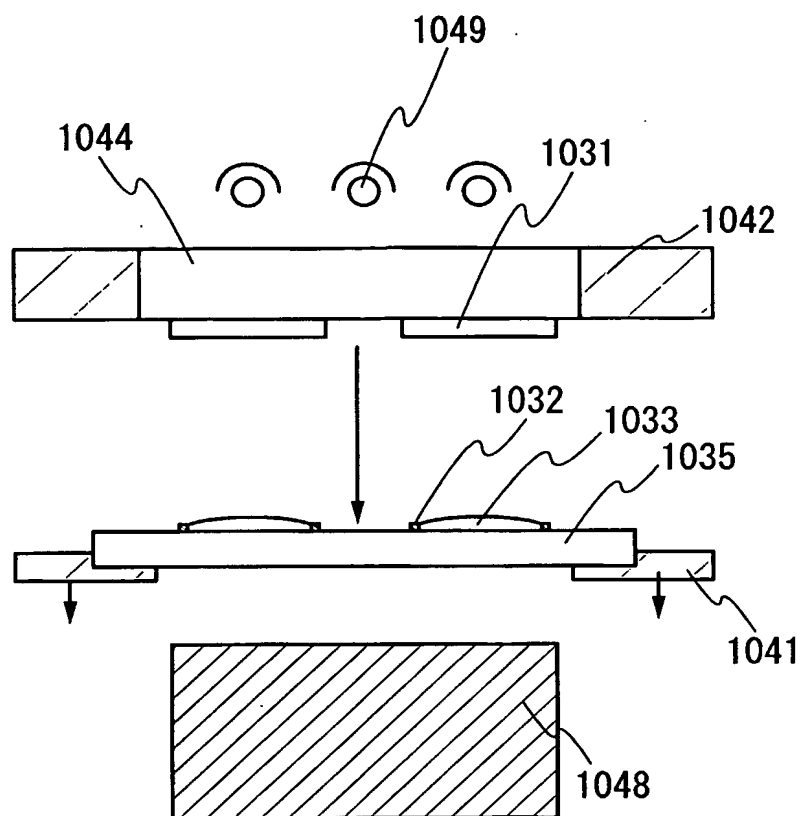


FIG.12

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(A)



(B)

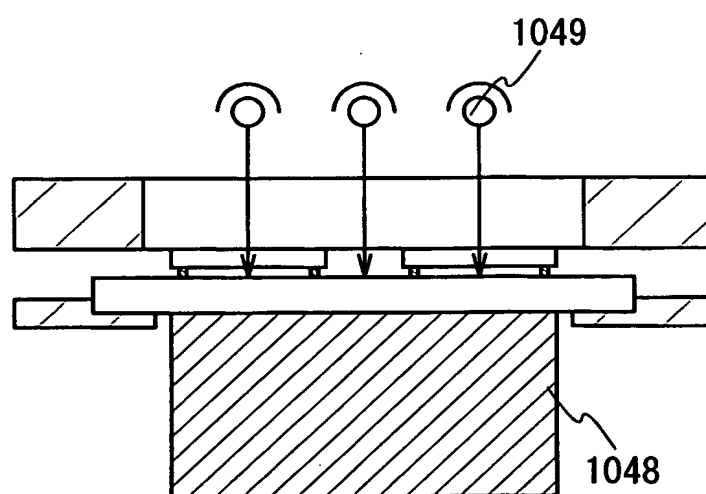


FIG.13

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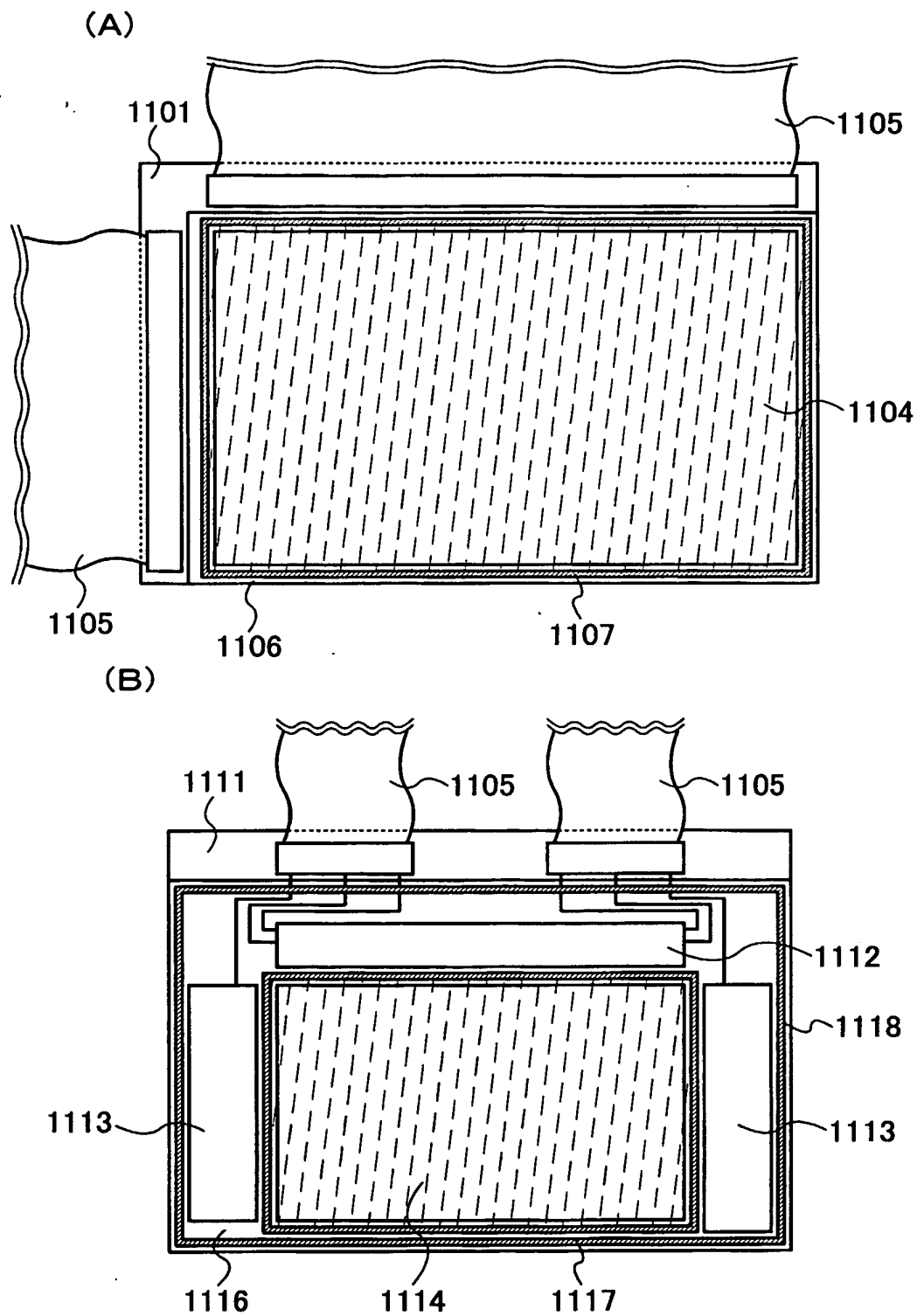


FIG.14

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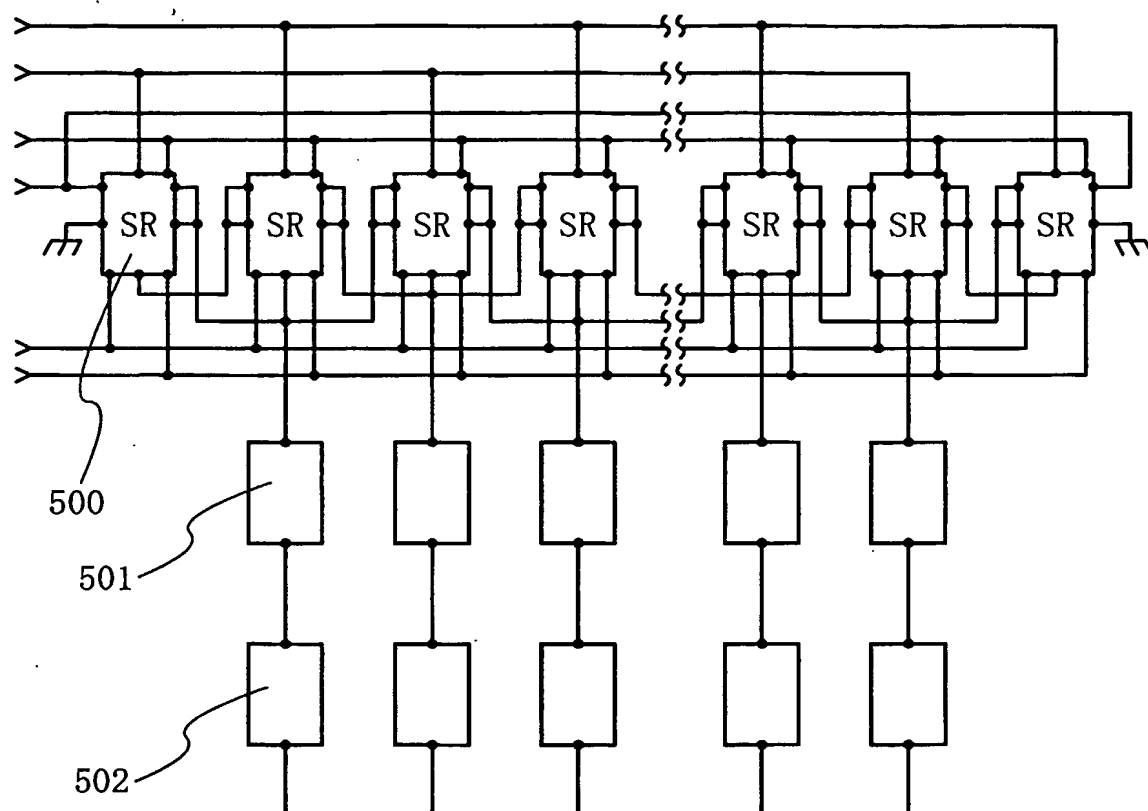


FIG.15

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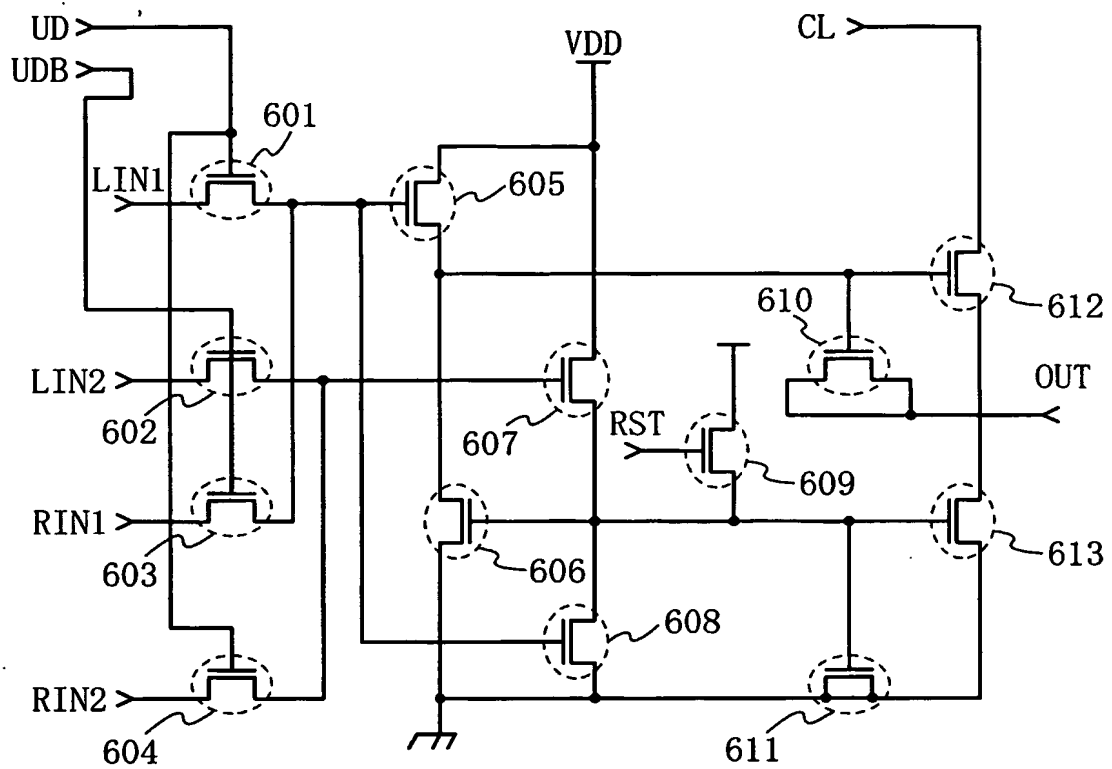


FIG.16



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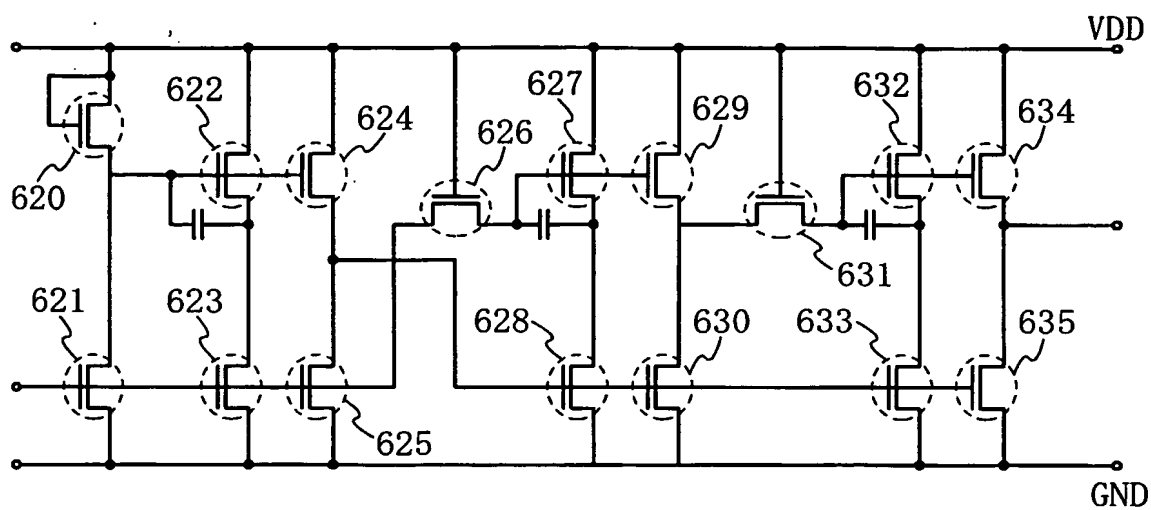


FIG.17

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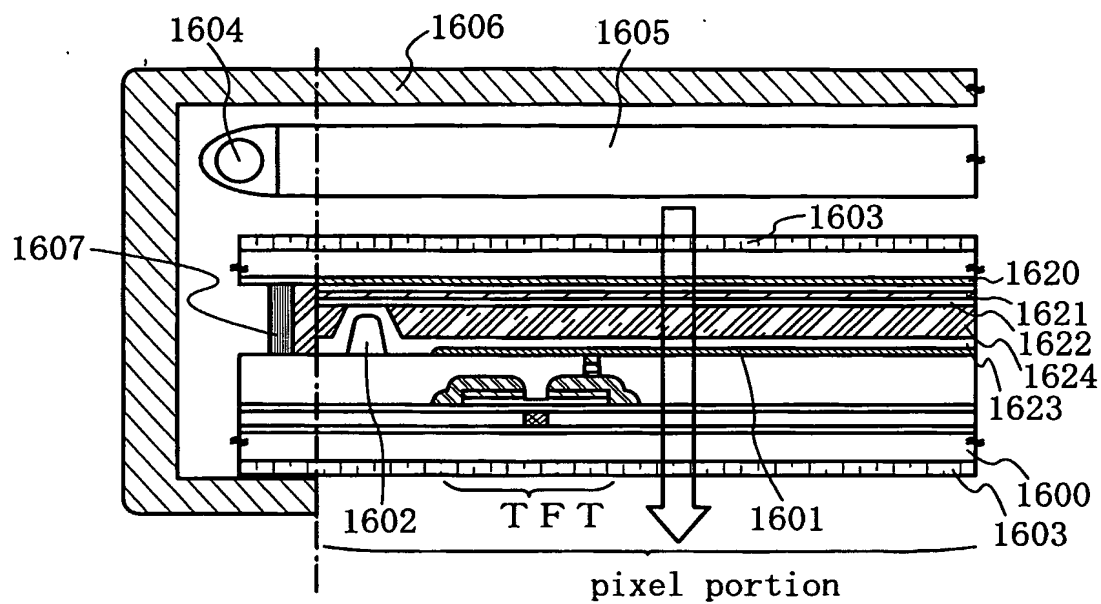


FIG.18

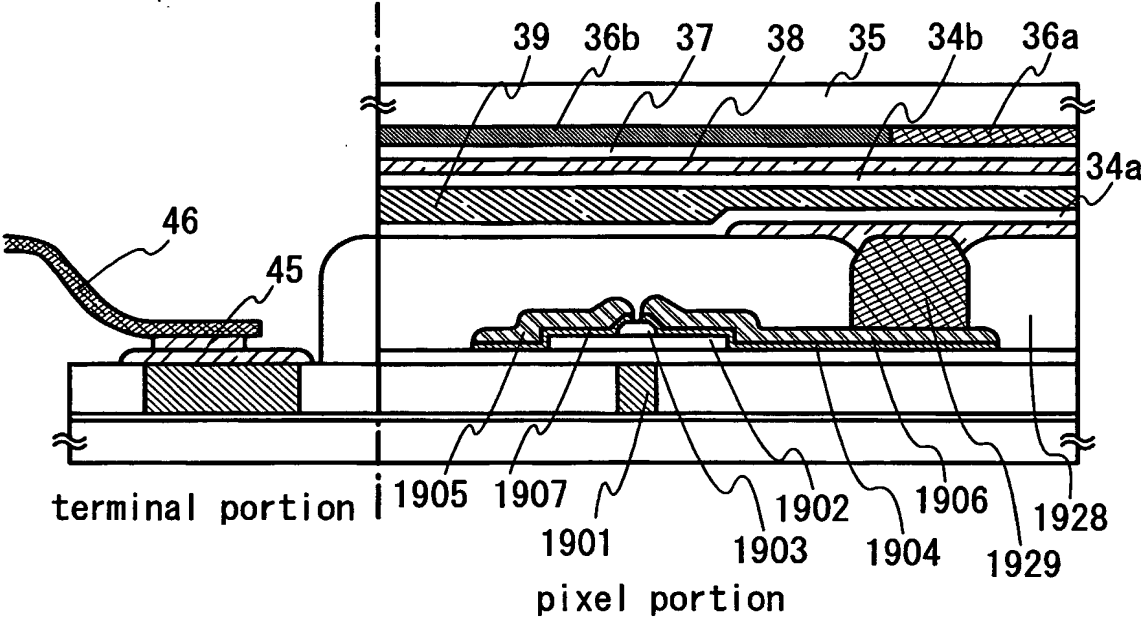


FIG.19

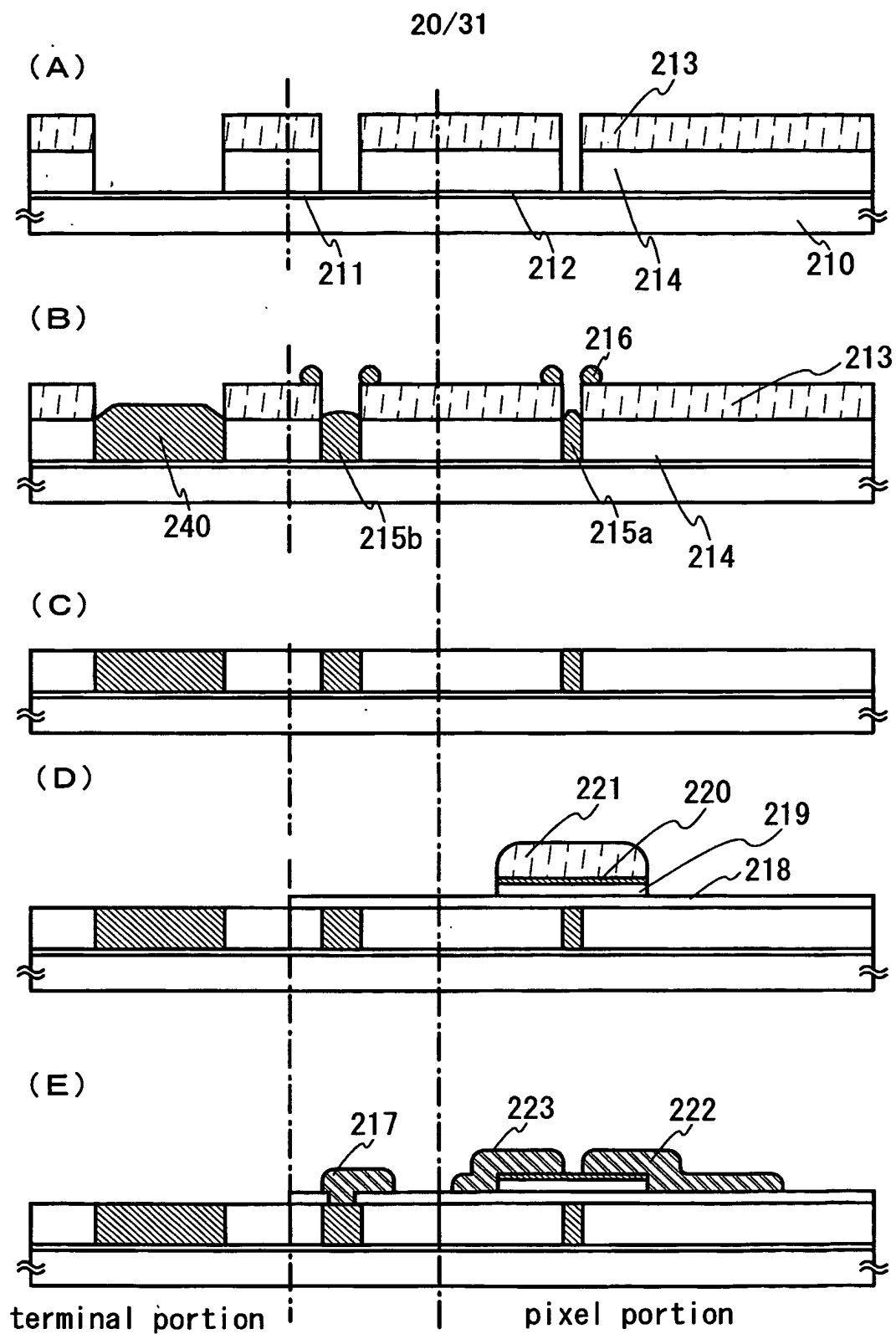


FIG.20

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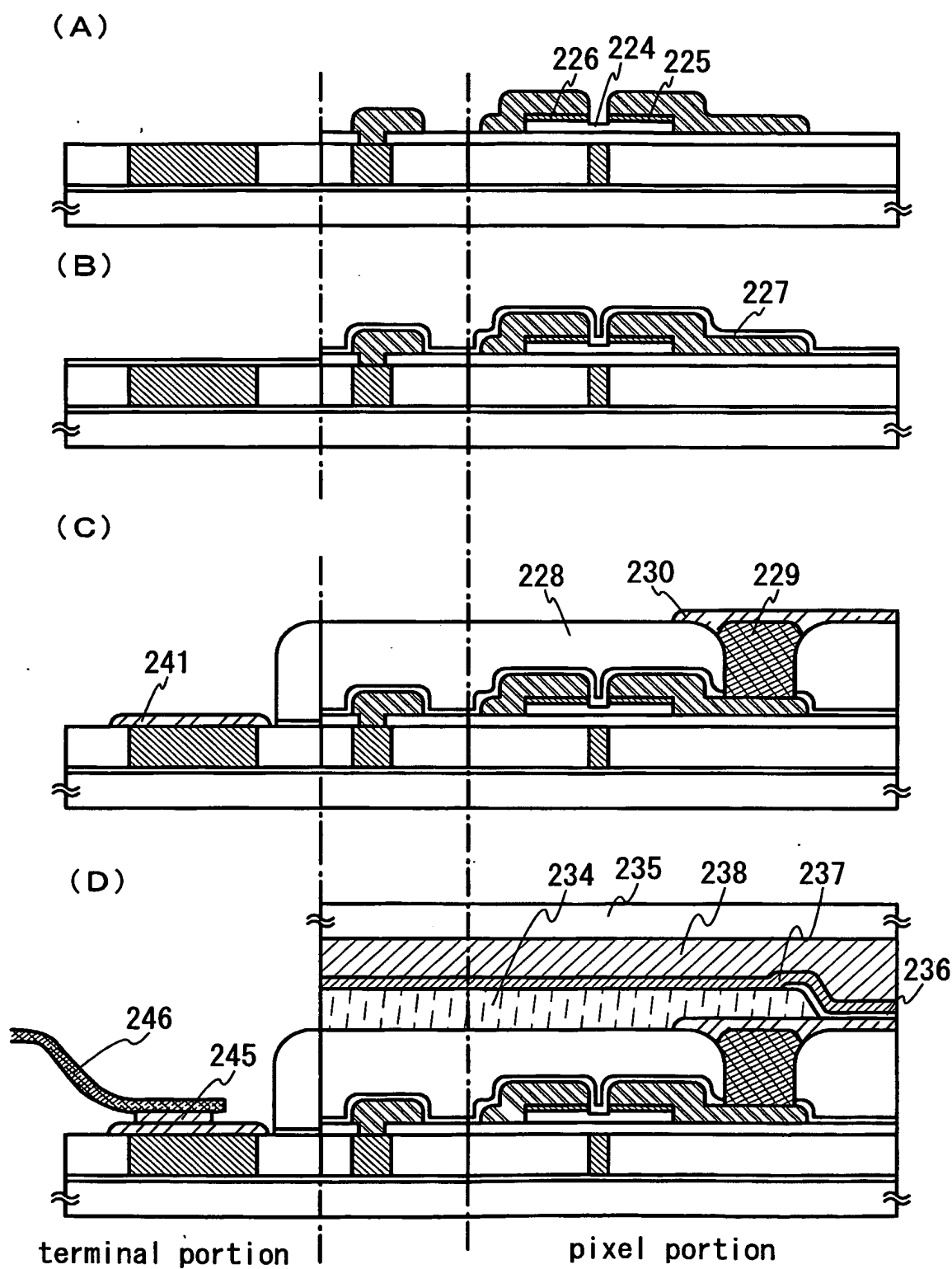


FIG.21

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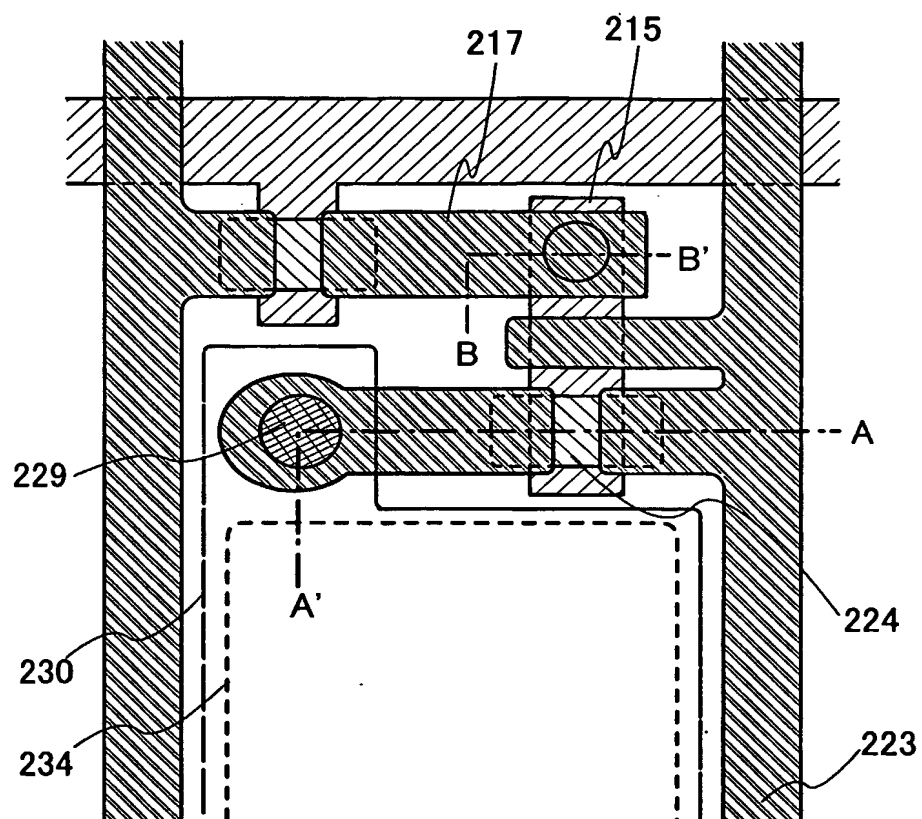


FIG.22

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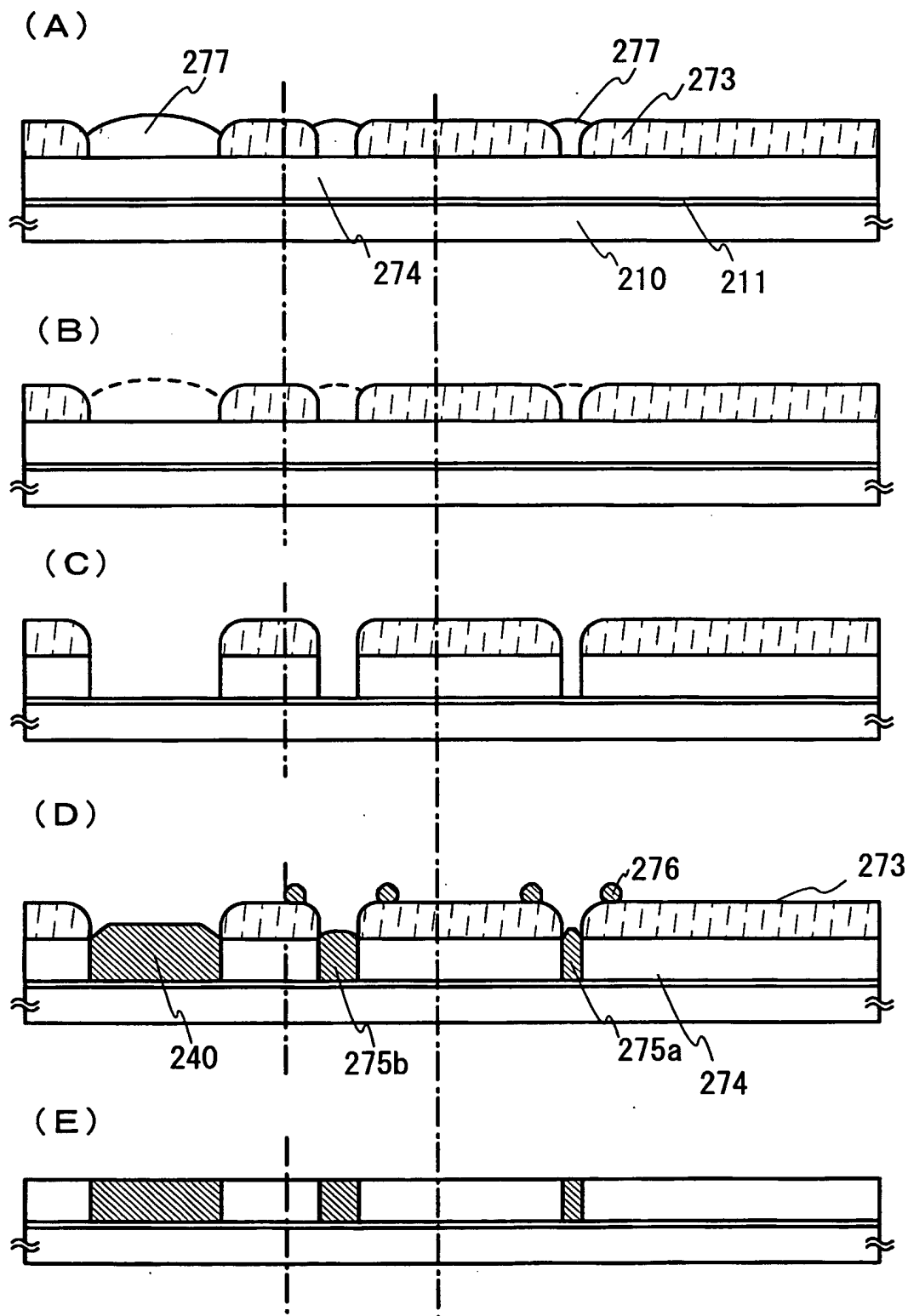


FIG.23

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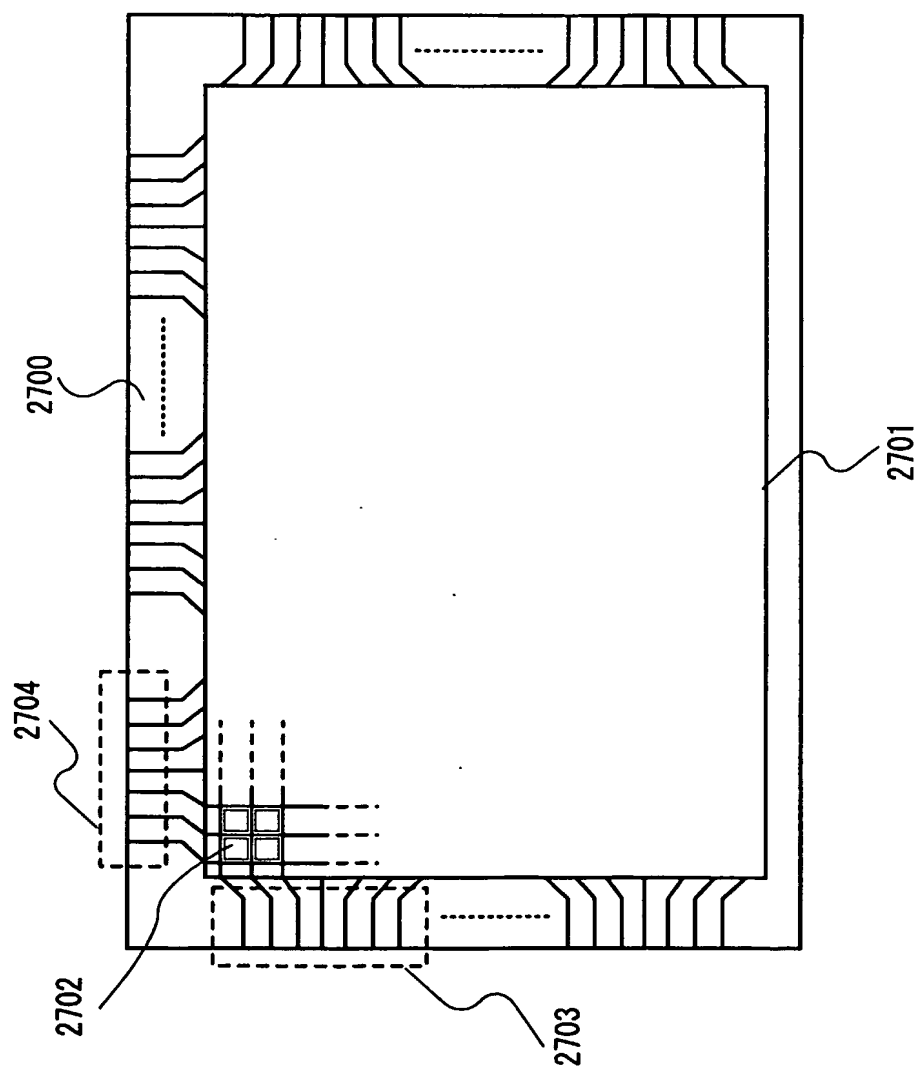


FIG. 24



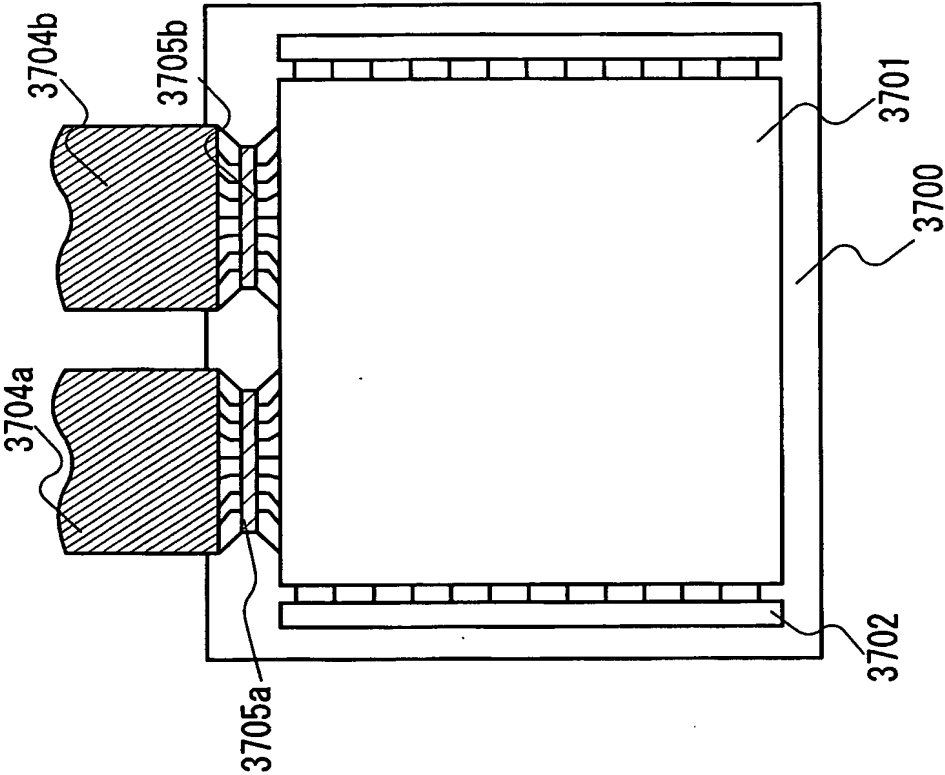


FIG.25

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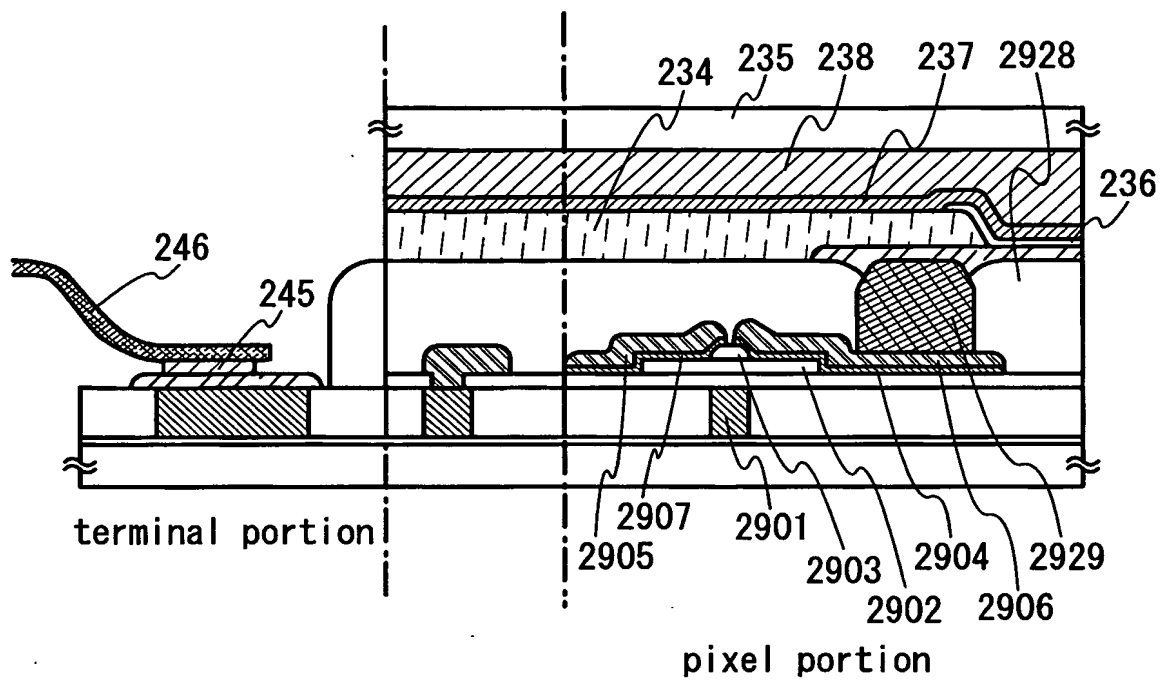


FIG.26

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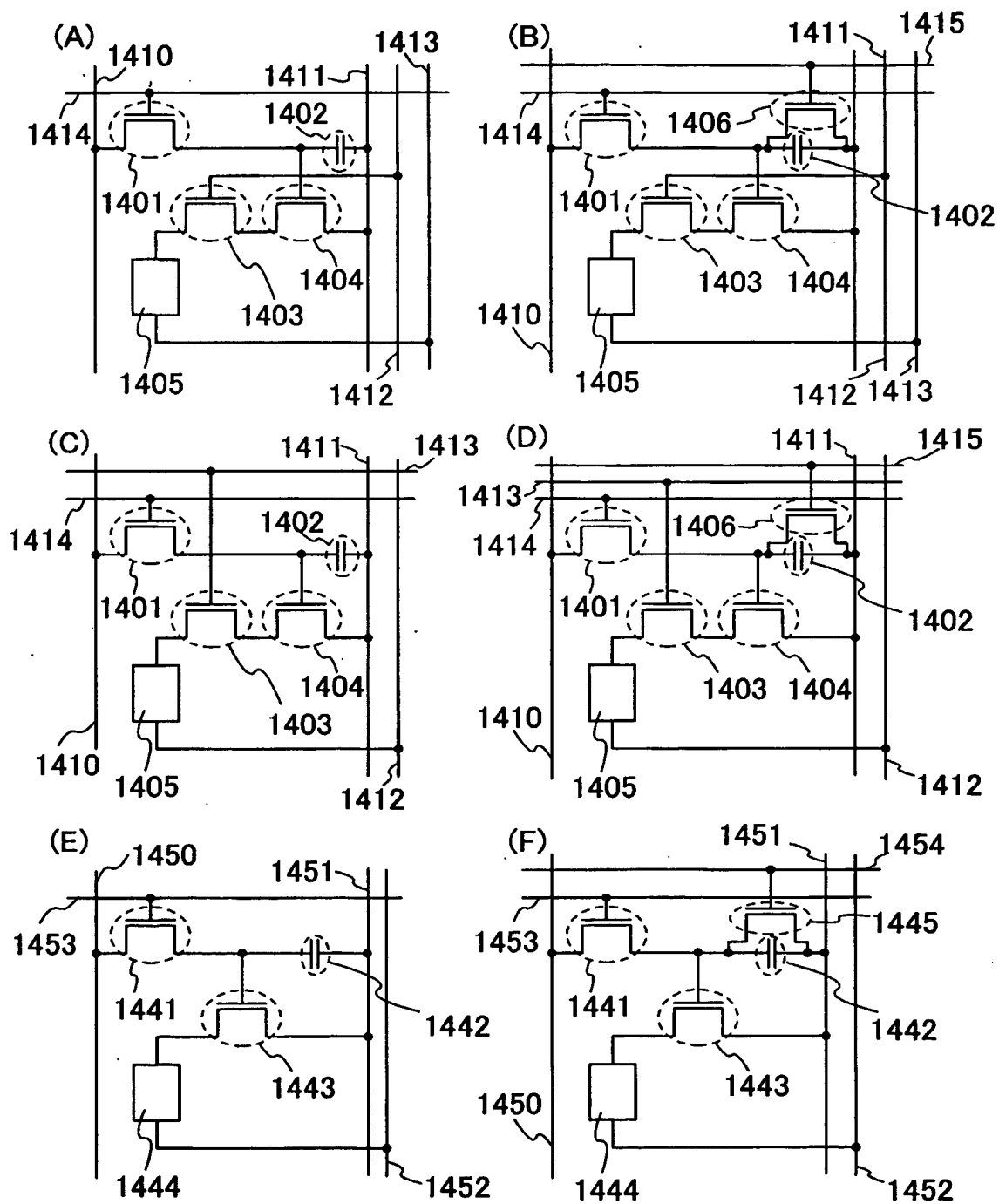
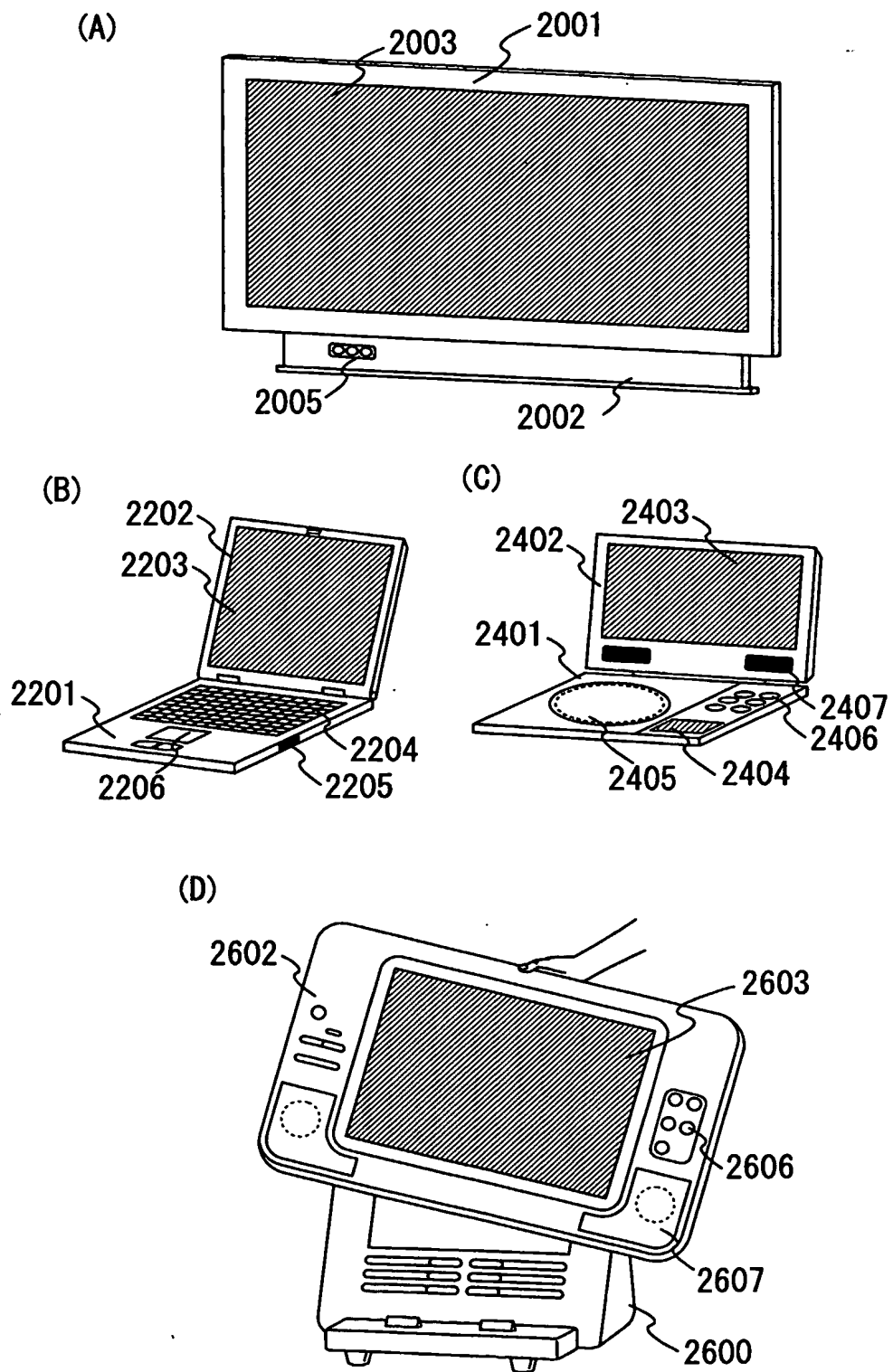


FIG.27

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EXPLANATION OF REFERENCE

10 substrate; 11 base layer; 12 depression; 13 mask; 14 Insulating layer; 15 Metal wiring; 16 Extra droplet; 18 Gate insulating film; 19 Semiconductor film; 20 N-type semiconductor film; 21 Mask; 22 Source wiring or a drain wiring; 23 Source wiring or a drain wiring; 24 Channel formation region; 25 Drain region; 26 Source region; 27 Protective film; 28 Interlayer insulating film; 29 Pillar; 30 Pixel electrode; 34a Orientation film ; 34b Orientation film; 35 Counter substrate; 36a Colored layer; 36b Light-shielding layer; 37 Over coat layer; 38 Counter electrode; 39 Liquid crystal; 40 Wiring; 41 Terminal electrode; 45 Anisotropic conductive layer; 46 FPC; 51 Substrate; 52 Hot plate; 53 Hot plate; 54 Top plate; 55a Support; 55b Support; 56 Teflon coat film; 57 Layer to be processed; 58a Heater; 58b Heater; 61 Substrate; 62 Roller; 63 Feed roller; 64 Roller conveyer; 66 Teflon coat film; 67 Layer to be processed; 73 Mask; 74 Insulating layer; 75 Wiring; 76 Extra droplet; 77 Water soluble resin; 110 Large-area substrate ; 111 Pixel portion; 112 Sealing portion; 113 Nozzle scan direction; 114 Material solution; 115 Object surface; 116 Droplet discharge device; 118 Nozzle; 119 Portion surrounded with a dotted line; 120 Inverted staggered type TFT; 121 Pixel electrode; 210 Substrate; 211 Base layer; 212 Depression; 213 Mask; 214 Insulating layer; 215a Metal wiring; 215b Metal wiring; 216 Droplet; 217 Lead-out electrode; 218 Gate insulating film; 219 Semiconductor film; 220 N-type semiconductor film; 221 Mask; 222 Source wiring or a drain wiring; 223 Source wiring or a drain wiring; 224 Channel formation region; 225 Drain region; 226 Source region; 227 Protective film; 228 Interlayer insulating film; 229 Pillar; 230 First electrode; 234 Partition; 235 Sealing substrate; 236 Layer containing an organic

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compound; 237 Second electrode; 238 Filler; 240 Wiring; 241 Terminal electrode; 245 Anisotropic conductive film; 246 FPC; 273 Mask; 274 Insulating layer; 275a Wiring; 275b Wiring; 276 Extra droplet; 277 Water soluble resin; 300 Large-area substrate; 302 Pixel portion; 303 Resist film; 380 Resist separation solution nozzle; 381 Resist separation solution nozzles; 382 Deionized water nozzles; 383 Blow nozzles; 384a Substrate support; 411 Base layer; 414 Insulating layer; 415a Gate electrode; 415b Gate wiring; 418 Gate insulating film; 422 Drain electrode; 423 Source electrode; 424 Semiconductor film; 428 Interlayer insulating film; 429 Pillar; 430 Pixel electrode; 500 Pulse output circuit; 501 Buffer circuit; 502 a pixel; 601 N-channel type TFT; 620 to 635 N-channel type TFT; 800 Nozzle unit; 801 Substrate; 802 First material layer; 803 Second material layer; 900 Substrate; 901 CVD device; 902 CVD device; 903 CVD device; 904 substrate transportation path; 1031 Second substrate; 1032 Sealant; 1033 Liquid crystal; 1034 Pixel portion; 1035 First substrate; 1041 First substrate support; 1042 Second substrate support; 1044 Window; 1048 Bottom downside base plate; 1049 Light source; 1101 Substrate; 1104 Pixel portion; 1105 FPC; 1106 Counter substrate; 1107 Sealant; 1111 Substrate; 1112 Source signal line driver circuit; 1113 Gate signal line driver circuit; 1114 Pixel portion; 1115 FPC; 1116 Counter substrate; 1117 First sealant; 1118 Second sealant; 1401 Switching TFT; 1402 Capacitor element; 1403 Driving TFT; 1404 Current control TFT; 1405 Light emitting element; 1406 TFT; 1410 Signal line; 1411 Power source line; 1412 Power source line; 1413 Power source line; 1414 Scan line; 1415 Power source line; 1416 Scan line; 1441 Switching TFT; 1442 Capacitor element; 1443 Driving TFT; 1444 Light emitting element; 1445 TFT; 1450 Signal line; 1451 Power source line; 1452 Power source line; 1453 Scan line; 1454 Scan line; 1500 Large-sized substrate; 1503 Region where one panel is formed;

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1504 Imaging unit; 1505a Head; 1505b Head; 1505c Head; 1507 Stage; 1511 Marker;  
1600 Substrate; 1601 Pixel electrode; 1602 Spacer; 1603 Orientation film; 1604 Back  
light; 1605 Light conducting plate; 1606 Cover; 1607 Sealant; 1620 Colored layer;  
1621 Counter electrode; 1622 Orientation film; 1623 Orientation film; 1624 Liquid  
5 crystal layer; 1901 Gate electrode; 1902 Semiconductor film; 1903 Channel protective  
layer; 1904 Source region or a drain region; 1905 Wiring; 1906 Wiring; 1907 Source  
region or a drain region; 1928 Interlayer insulating film; 1929 Pillar; 2001 Casing;  
2002 Support; 2003 Display portion; 2005 Video input terminal; 2201 Main body;  
2202 Casing; 2203 Display portion; 2204 Keyboard; 2205 External connection port;  
10 2206 Pointing mouse; 2401 Main body; 2402 Casing; 2403 Display portion A; 2404  
Display portion B; 2405 Recording medium reading part; 2406 Operation key; 2407  
Speaker unit; 2600 Charger; 2602 Casing; 2603 Display portion; 2604 Display portion;  
2606 Operation key; 2407 Speaker unit; 2700 Substrate; 2701 Pixel portion; 2702  
Pixel; 2703 Scan line side input terminal; 2704 Signal line side input terminal; 2901  
15 Gate electrode; 2902 Semiconductor film; 2903 Channel protective layer; 2904 Source  
region or a drain region; 2905 Wiring; 2906 Wiring; 2907 Source region or a drain  
region; 2928 Interlayer insulating film; 2929 Pillar; 3700 Substrate; 3701 Pixel  
portion; 3702 Driver circuit; 3704a Tape; 3704b Tape; 3705a Driver IC; 3705b Driver  
IC